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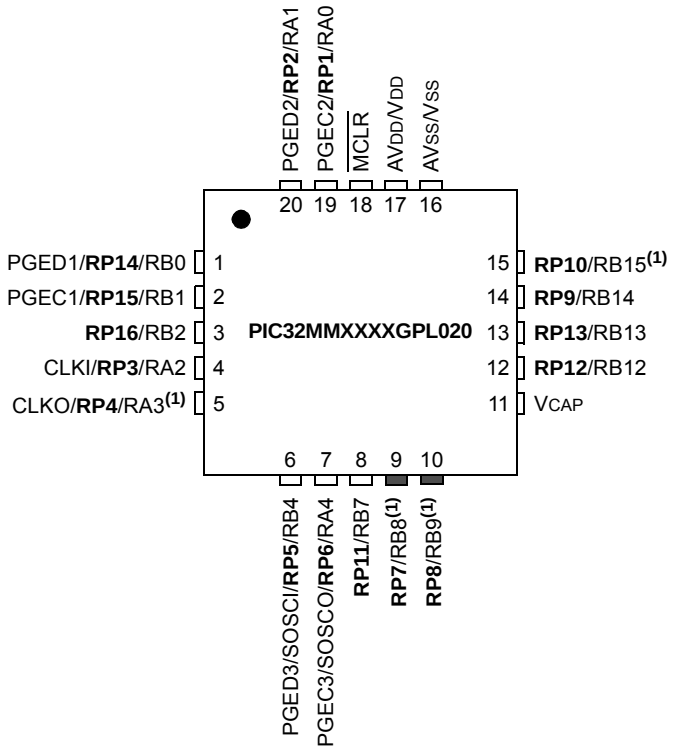
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® microAptiv™
Core Size	32-Bit Single-Core
Speed	25MHz
Connectivity	IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, I²S, POR, PWM, WDT
Number of I/O	29
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 14x10/12b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-VFQFN Exposed Pad
Supplier Device Package	36-SQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mm0032gpl036t-i-m2

Pin Diagrams (Continued)

20-Pin QFN



Legend: Shaded pins are up to 5V tolerant.

Note 1: Pin has an increased current drive strength. Refer to **Section 26.0 "Electrical Characteristics"** for details.

TABLE 3: COMPLETE PIN FUNCTION DESCRIPTIONS FOR 20-PIN QFN DEVICES

Pin	Function	Pin	Function
1	PGED1/AN2/C1IND/C2INB/**RP14**/RB0	11	VCAP
2	PGEC1/AN3/C1INC/C2INA/**RP15**/RB1	12	TDO/AN7/LVDIN/**RP12**/RB12
3	AN4/**RP16**/RB2	13	TDI/AN8/**RP13**/RB13
4	OSC1/CLKI/AN5/C1INB/**RP3**/OCM1C/RA2	14	CDAC1/AN9/**RP9**/RTCC/U1TX/SDI1/C1OUT/INT1/RB14
5	OSC2/CLKO/AN6/C1INA/**RP4**/OCM1D/RA3(1)	15	AN10/REFCLKO/**RP10**/U1RX/$\overline{SS1}$/FSYNC1/INT0/RB15(1)
6	PGED3/SOSCI/**RP5**/RB4	16	AVSS/VSS
7	PGEC3/SOSCO/SCLKI/**RP6**/PWRLCLK/RA4	17	AVDD/VDD
8	**RP11**/RB7	18	$\overline{MCLR}$
9	TCK/**RP7**/$\overline{U1CTS}$/SCK1/OCM1A/RB8(1)	19	PGEC2/VREF+/AN0/**RP1**/OCM1E/INT3/RA0
10	TMS/REFCLKI/**RP8**/T1CK/T1G/$\overline{U1RTS}$/U1BCLK/SDO1/C2OUT/OCM1B/INT2/RB9(1)	20	PGED2/VREF-/AN1/**RP2**/OCM1F/RA1

Note 1: Pin has an increased current drive strength.

TABLE 1-1: PIC32MM0064GPL036 FAMILY PINOUT DESCRIPTION (CONTINUED)

Pin Name	Pin Number						Pin Type	Buffer Type	Description
	20-Pin QFN	20-Pin SSOP	28-Pin QFN/ UQFN	28-Pin SPDIP/ SSOP/SOIC	36-Pin VQFN	40-Pin UQFN			
VCAP	11	14	17	20	22	24	P	—	Core voltage regulator filter capacitor connection
VDD	17	20	10,25	13,28	13,23,31	13,26, 34	P	—	Digital modules power supply
VREF-	20	3	28	3	34	37	I	ANA	ADC negative reference
VREF+	19	2	27	2	33	36	I	ANA	ADC and DAC positive reference
VSS	16	19	5,24	8,27	6,12,30	6,12, 33	P	—	Digital modules ground

Legend: ST = Schmitt Trigger input buffer DIG = Digital input/output ANA = Analog level input/output

NOTES:

3.2 Architecture Overview

The MIPS32® microAptiv™ UC microprocessor core in the PIC32MM0064GPL036 family devices contains several logic blocks, working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- General Purpose Register (GPR)
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Memory Management Unit (MMU)
- Power Management
- microMIPS Instructions Decoder
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous Multiply/Divide Unit (MDU). The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. One additional register file shadow set (containing thirty-two registers) is added to minimize context switching overhead during interrupt/exception processing. The register file consists of two read ports and one write port, and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid Stalls when executing instruction streams where data producing instructions are followed closely by consumers for their results
- Leading zero/one detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing arithmetic and bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The microAptiv UC core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows the long-running MDU operations to be partially masked by system Stalls and/or other Integer Unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, Result/Accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the rs operand. The second number ('16' of 32x16) represents the rt operand. The microAptiv UC core only checks the value of the rt operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

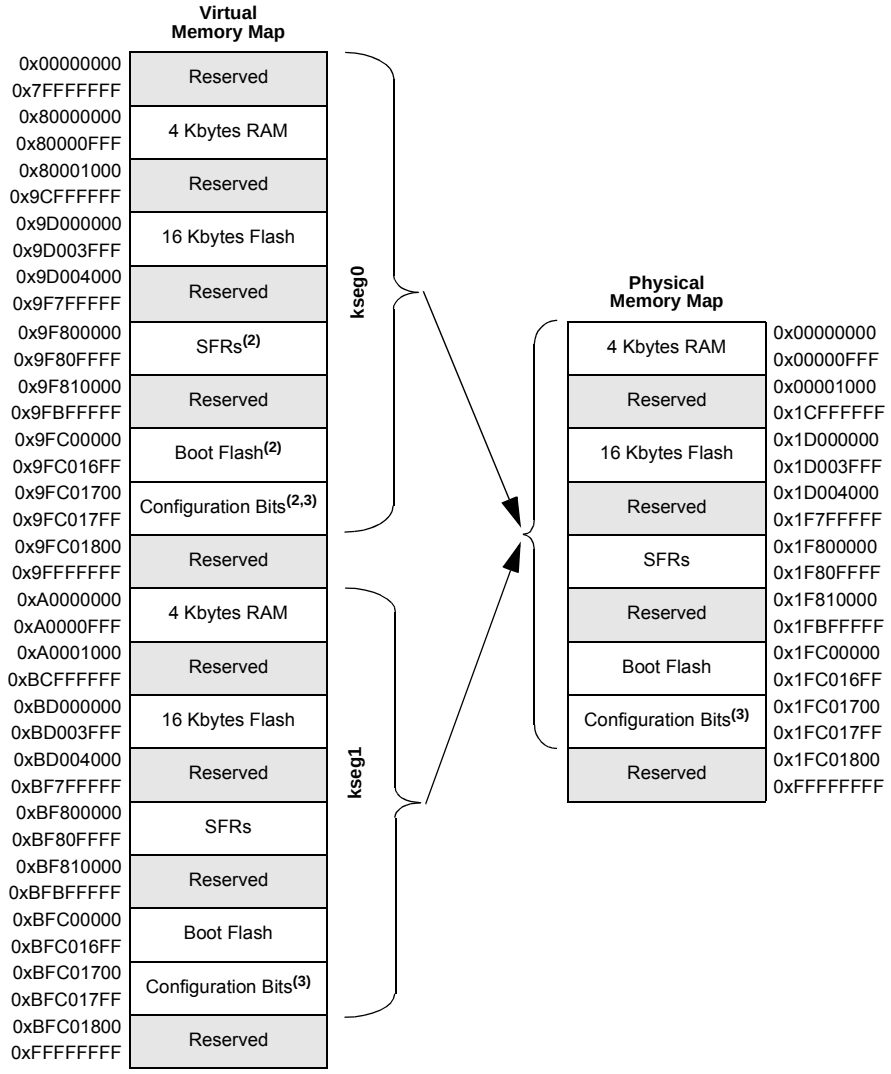
The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back, 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU. Divide operations are implemented with a simple 1-bit-per-clock iterative algorithm. An early-in detection checks the sign extension of the dividend (rs) operand. If rs is 8 bits wide, 23 iterations are skipped. For a 16-bit wide rs, 15 iterations are skipped, and for a 24-bit wide rs, 7 iterations are skipped. Any attempt to issue a subsequent MDU instruction while a divide is still active causes an IU pipeline Stall until the divide operation has completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be re-issued), and latency (number of cycles until a result is available) for the microAptiv UC core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU`, `MADD/MADDU`, `MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL` (GPR destination)	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

FIGURE 4-1: MEMORY MAP FOR DEVICES WITH 16 Kbytes OF PROGRAM MEMORY(1)



Note 1: Memory areas are not shown to scale.

2: This region should be accessed from kseg1 space only.

3: Primary Configuration bits area is located at the address range, from 0x1FC01780 to 0x1FC017E8. Alternate Configuration bits area is located at the address range, from 0x1FC01700 to 0x1FC01768. Refer to **Section 4.1 "Alternate Configuration Bits Space"** for more information.

REGISTER 5-1: NVMCON: NVM PROGRAMMING CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0, HC	R/W-0	R-0, HS, HC	R-0, HS, HC	r-0	U-0	U-0	U-0
	WR(1,4)	WREN(1)	WRERR(1,2)	LVDERR(1,2)	—	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	NVMOP<3:0>(3)			

Legend:	HS = Hardware Settable bit	HC = Hardware Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	r = Reserved bit

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **WR:** Write Control bit(1,4)
This bit cannot be cleared and can be set only when WREN = 1, and the unlock sequence has been performed.
1 = Initiates a Flash operation
0 = Flash operation is complete or inactive

bit 14 **WREN:** Write Enable bit(1)
1 = Enables writes to the WR bit and disables writes to the NVMOP<3:0> bits
0 = Disables writes to the WR bit and enables writes to the NVMOP<3:0> bits

bit 13 **WRERR:** Write Error bit(1,2)
This bit can be cleared only by setting the NVMOP<3:0> bits = 0000 and initiating a Flash operation.
1 = Program or erase sequence did not complete successfully
0 = Program or erase sequence completed normally

bit 12 **LVDERR:** Low-Voltage Detect Error bit(1,2)
This bit can be cleared only by setting the NVMOP<3:0> bits = 0000 and initiating a Flash operation.
1 = Low voltage is detected (possible data corruption if WRERR is set)
0 = Voltage level is acceptable for programming

bit 11 **Reserved:** Maintain as '0'

bit 10-4 **Unimplemented:** Read as '0'

Note 1: These bits are only reset by a Power-on Reset (POR) and are not affected by other Reset sources.
2: These bits are cleared by setting NVMOP<3:0> = 0000 and initiating a Flash operation (i.e., WR).
3: NVMOP<3:0> bits are write-protected if the WREN bit is set.
4: Writes to the WR bit require an unlock sequence. Refer to **Section 5.1 "Flash Controller Registers Write Protection"** for details.

REGISTER 7-3: INTSTAT: INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC
	—	—	—	—	—	SRIPL<2:0>(1)		
7:0	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC	R-0, HS, HC
	SIRQ<7:0>							

Legend:	HS = Hardware Settable bit	HC = Hardware Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-11 **Unimplemented:** Read as '0'

bit 10-8 **SRIPL<2:0>:** Requested Priority Level for Single Vector Mode bits(1)

111-000 = The priority level of the latest interrupt presented to the CPU

bit 7-0 **SIRQ<7:0>:** Last Interrupt Request Serviced Status bits

11111111-00000000 = The last interrupt request number serviced by the CPU

Note 1: This value should only be used when the interrupt controller is configured for Single Vector mode.

REGISTER 7-4: IPTMR: INTERRUPT PROXIMITY TIMER REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IPTMR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IPTMR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IPTMR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	IPTMR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **IPTMR<31:0>:** Interrupt Proximity Timer Reload bits

Used by the interrupt proximity timer as a reload value when the interrupt proximity timer is triggered by an interrupt event.

8.0 OSCILLATOR CONFIGURATION

Note: This data sheet summarizes the features of the PIC32MM0064GPL036 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 59. "Oscillators with DCO"** (DS60001329) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). The information in this data sheet supersedes the information in the FRM.

The PIC32MM0064GPL036 family oscillator system has the following modules and features:

- On-Chip PLL with User-Selectable Multiplier and Output Divider to Boost Operating Frequency on Select Internal and External Oscillator Sources
- Primary High-Frequency Crystal Oscillator
- Secondary Low-Frequency and Low-Power Crystal Oscillator
- On-Chip Fast RC (FRC) Oscillator with User-Selectable Output Divider
- Software-Controllable Switching between Various Clock Sources
- Fail-Safe Clock Monitor (FSCM) that Detects Clock Failure and Permits Safe Application Recovery or Shutdown
- Flexible Reference Clock Output (REFO)

A block diagram of the oscillator system is provided in Figure 8-1.

8.1 Fail-Safe Clock Monitor (FSCM)

The PIC32MM0064GPL036 family oscillator system includes a Fail-Safe Clock Monitor (FSCM). The FSCM monitors the SYSCLK for continuous operation. If it detects that the SYSCLK has failed, it switches the SYSCLK over to the FRC oscillator and triggers a Non-Maskable Interrupt (NMI). When the NMI is executed, software can attempt to restart the main oscillator or shut down the system.

In Sleep mode, both the SYSCLK and the FSCM halt, which prevents FSCM detection.

10.0 TIMER1

Note: This data sheet summarizes the features of the PIC32MM0064GPL036 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32). The information in this data sheet supersedes the information in the FRM.

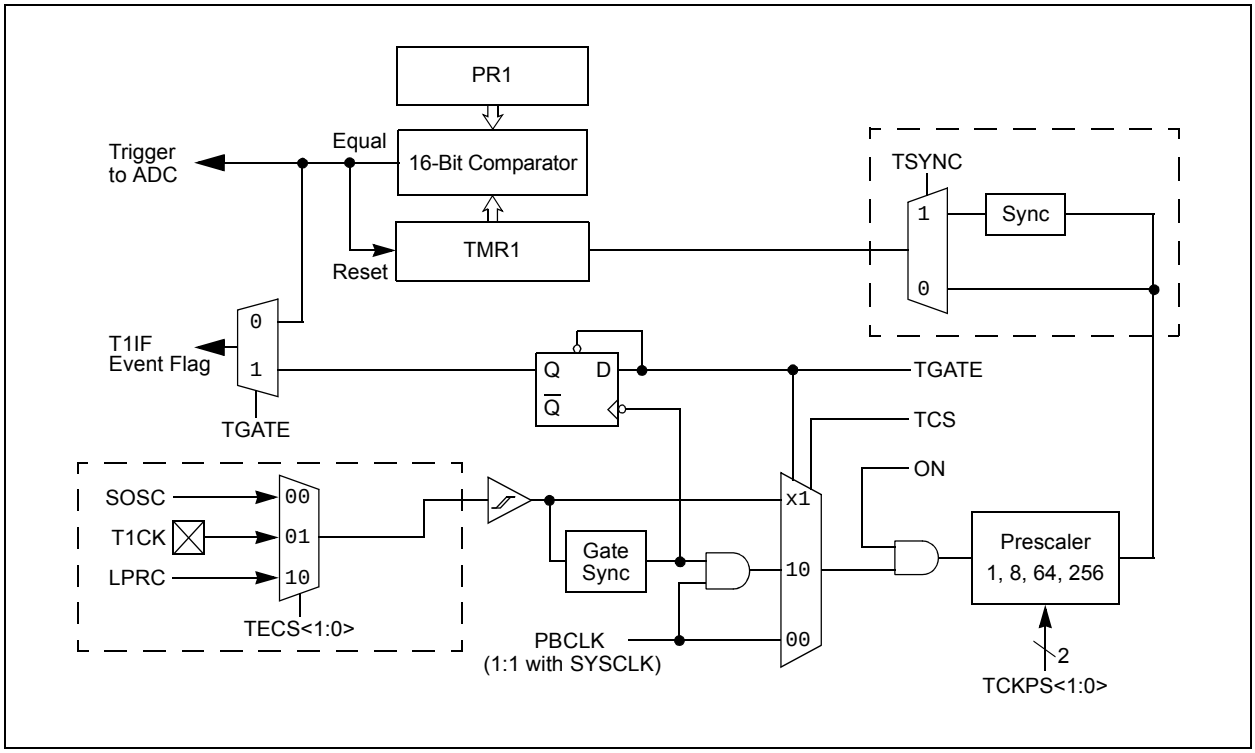
PIC32MM0064GPL036 family devices feature one synchronous/asynchronous 16-bit timer that can operate as a free-running interval timer for various timing applications and counting external events. This timer can be clocked from different sources, such as the Peripheral Bus Clock (PBCLK, 1:1 with SYSCLK), Secondary Oscillator (SOSC), T1CK pin or LPRC oscillator.

The following modes are supported by Timer1:

- Synchronous Internal Timer
- Synchronous Internal Gated Timer
- Synchronous External Timer
- Asynchronous External Timer

The timer has a selectable clock prescaler and can operate in Sleep and Idle modes.

FIGURE 10-1: TIMER1 BLOCK DIAGRAM



10.1 Timer1 Control Register

TABLE 10-1: TIMER1 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
8000	T1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	TWDIS	TWIP	—	TECS<1:0>		TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—	0000
8010	TMR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	TMR1<15:0>																0000
8020	PR1	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PR1<15:0>																FFFF

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively.

REGISTER 12-1: CCPxCON1: CAPTURE/COMPARE/PWMx CONTROL 1 REGISTER (CONTINUED)

bit 20-16 **SYNC<4:0>:** CCPx Synchronization Source Select bits
11111 = Timer is in the Free-Running mode and rolls over at FFFFh (Timer Period register is ignored)
11110 = Reserved
. . .
11100 = Reserved
11011 = Time base is synchronized to the start of ADC conversion
11010 = Reserved
11001 = Time base is synchronized to Comparator 2
11000 = Time base is synchronized to Comparator 1
10111 = Reserved
. . .
10010 = Reserved
10001 = Time base is synchronized to CLC2
10001 = Time base is synchronized to CLC1
01111 = Reserved
01110 = Reserved
01101 = Time base is synchronized to the INT4 pin (remappable)
01100 = Time base is synchronized to the INT3 pin
01011 = Time base is synchronized to the INT2 pin
01010 = Time base is synchronized to the INT1 pin
01001 = Time base is synchronized to the INT0 pin
01000 = Reserved
. . .
00101 = Reserved
00100 = Time base is synchronized to SCCP3
00011 = Time base is synchronized to SCCP2
00010 = Time base is synchronized to MCCP1
00001 = Time base is synchronized to this MCCP/SCCP
00000 = No external synchronization; timer rolls over at FFFFh or matches with the Timer Period register

bit 15 **ON:** CCPx Module Enable bit(1)
1 = Module is enabled with the operating mode specified by the MOD<3:0> bits
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** CCPx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **CCPSLP:** CCPx Sleep Mode Enable bit
1 = Module continues to operate in Sleep modes
0 = Module does not operate in Sleep modes

bit 11 **TMRSYNC:** Time Base Clock Synchronization bit
1 = Module time base clock is synchronized to internal system clocks; timing restrictions apply
0 = Module time base clock is not synchronized to internal system clocks

bit 10-8 **CLKSEL<2:0>:** CCPx Time Base Clock Select bits
111 = TCKIA pin (remappable)
110 = TCKIB pin (remappable)
101 = Reserved
100 = Reserved
011 = CLC1 output for MCCP1 and SCCP2/CLC2 output for SCCP3
010 = Secondary Oscillator (SOSC) clock
001 = REFCLKO output clock
000 = System clock (FSYS)

Note 1: This control bit has no function in Input Capture modes.
2: This control bit has no function when TRIGEN = 0.
3: Values greater than '0011' will cause a FIFO buffer overflow in Input Capture mode.

REGISTER 15-1: RTCCON1: RTCC CONTROL 1 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	ALRMEN	CHIME	—	—	AMASK<3:0>			
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ALMRPT<7:0>(1)							
15:8	R/W-0	U-0	U-0	U-0	R/W-0	U-0	U-0	U-0
	ON	—	—	—	WRLOCK(2)	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
	RTCOE	OUTSEL<2:0>			—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **ALRMEN:** Alarm Enable bit
1 = Alarm is enabled
0 = Alarm is disabled

bit 30 **CHIME:** Chime Enable bit
1 = Chime is enabled; ALMRPT<7:0> bits are allowed to underflow from '00' to 'FF'
0 = Chime is disabled; ALMRPT<7:0> bits stop once they reach '00'

bit 29-28 **Unimplemented:** Read as '0'

bit 27-24 **AMASK<3:0>:** Alarm Mask Configuration bits
11xx = Reserved, do not use
101x = Reserved, do not use
1001 = Once a year (or once every 4 years when configured for February 29th)
1000 = Once a month
0111 = Once a week
0110 = Once a day
0101 = Every hour
0100 = Every 10 minutes
0011 = Every minute
0010 = Every 10 seconds
0001 = Every second
0000 = Every half second

bit 23-16 **ALMRPT<7:0>:** Alarm Repeat Counter Value bits(1)
11111111 = Alarm will repeat 255 more times
11111110 = Alarm will repeat 254 more times
• • •
00000010 = Alarm will repeat 2 more times
00000001 = Alarm will repeat 1 more time
00000000 = Alarm will not repeat

bit 15 **ON:** RTCC Enable bit
1 = RTCC is enabled and counts from selected clock source
0 = RTCC is disabled

bit 14-12 **Unimplemented:** Read as '0'

Note 1: The counter decrements on any alarm event. The counter is prevented from rolling over from '00' to 'FF' unless CHIME = 1.

2: To clear this bit, an unlock sequence is required. Refer to **Section 23.4 "System Registers Write Protection"** for details.

REGISTER 18-1: CLCxCON: CLCx CONTROL REGISTER (CONTINUED)

bit 5 **LCPOL:** CLCx Output Polarity Control bit
1 = The output of the module is inverted
0 = The output of the module is not inverted

bit 4-3 **Unimplemented:** Read as '0'

bit 2-0 **MODE<2:0>:** CLCx Mode bits
111 = Cell is a 1-input transparent latch with S and R
110 = Cell is a JK flip-flop with R
101 = Cell is a 2-input D flip-flop with R
100 = Cell is a 1-input D flip-flop with S and R
011 = Cell is an SR latch
010 = Cell is a 4-input AND
001 = Cell is an OR-XOR
000 = Cell is a AND-OR

Note 1: The INTP and INTN bits should not be set at the same time for proper interrupt functionality.

REGISTER 20-1: DAC1CON: CDAC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	DACDAT<4:0>				
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	ON	—	—	—	—	—	—	DACOE
7:0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	REFSEL<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-21 **Unimplemented:** Read as '0'

bit 20-16 **DACDAT<4:0>:** CDAC Voltage Reference Selection bits

11111 = (DACDAT<4:0> * VREF+/32) or (DACDAT<4:0> * AVDD/32) volts depending on the REFSEL<1:0> bits
•
•
•
00000 = 0.0 volts

bit 15 **ON:** Voltage Reference Enable bit

1 = Voltage reference is enabled
0 = Voltage reference is disabled

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **DACOE:** CDAC Voltage Reference Output Enable bit

1 = Voltage level is output on the CDAC1 pin
0 = Voltage level is disconnected from the CDAC1 pin

bit 7-2 **Unimplemented:** Read as '0'

bit 1-0 **REFSEL<1:0>:** CDAC Voltage Reference Source Select bits

11 = Reference voltage is AVDD
10 = No reference is selected – output is AVSS
01 = Reference voltage is the VREF+ input pin voltage
00 = No reference is selected – output is AVSS

REGISTER 23-3: FPOR/AFPOR: POWER-UP SETTINGS CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
15:8	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
7:0	r-1	r-1	r-1	r-1	R/P	R/P	R/P	R/P
	—	—	—	—	LPBOREN	RETVR	BOREN<1:0>	

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-4 **Reserved:** Program as '1'

bit 3 **LPBOREN:** Low-Power BOR Enable bit
1 = Low-Power BOR is enabled when the main BOR is disabled
0 = Low-Power BOR is disabled

bit 2 **RETVR:** Retention Voltage Regulator Enable bit
1 = Retention regulator is disabled
0 = Retention regulator is enabled and controlled by the RETEN bit during Sleep

bit 1-0 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = Brown-out Reset is enabled in hardware; SBOREN bit is disabled
10 = Brown-out Reset is enabled only while device is active and is disabled in Sleep; SBOREN bit is disabled
01 = Brown-out Reset is controlled with the SBOREN bit setting
00 = Brown-out Reset is disabled in hardware; SBOREN bit is disabled

TABLE 26-5: IDLE CURRENT (I_{IDLE})(2)

Operating Conditions: -40°C < TA < +85°C (unless otherwise stated)					
Parameter No.	**Typical(1)**	**Max**	**Units**	**VDD**	**Conditions**
DC40	0.26	0.46	mA	2.0V	FSYS = 1 MHz
	0.26	0.46	mA	3.3V	
DC41	0.85	1.5	mA	2.0V	FSYS = 8 MHz
	0.85	1.5	mA	3.3V	
DC42	2.3	3.7	mA	2.0V	FSYS = 25 MHz
	2.3	3.7	mA	3.3V	
DC44	0.18	0.34	mA	2.0V	FSYS = 32 kHz
	0.18	0.34	mA	3.3V	

Note 1: Data in the "Typical" column is at +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base IIDLE current is measured with:

- Oscillator is configured in EC mode without PLL (FNOSC<2:0> (FOSCSEL<2:0>) = `010` and POSCMOD<1:0> (FOSCSEL<9:8>) = `00`)
- OSC1 pin is driven with external square wave with levels from 0.3V to VDD – 0.3V
- OSC2 is configured as I/O in Configuration Words (OSCIOFNC (FOSCSEL<10>) = `1`)
- FSCM is disabled (FCKSM<1:0> (FOSCSEL<15:14>) = `00`)
- Secondary Oscillator circuits are disabled (SOSCEN (FOSCSEL<6>) = `0` and SOSCSEL (FOSCSEL<12>) = `0`)
- Main and low-power BOR circuits are disabled (BOREN<1:0> (FPOR<1:0>) = `00` and LPBOREN (FPOR<3>) = `0`)
- Watchdog Timer is disabled (FWDTEN (FWDT<15>) = `0`)
- All I/O pins (excepting OSC1) are configured as outputs and driving low
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)

TABLE 26-8: I/O PIN INPUT SPECIFICATIONS

Operating Conditions: 2.0V ≤ VDD ≤ 3.6V, -40°C ≤ TA ≤ +85°C (unless otherwise stated)							
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage(2)**					
DI10		I/O Pins with ST Buffer	VSS	—	0.2 VDD	V	
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI16		OSC1/CLKI (XT mode)	VSS	—	0.2 VDD	V	
DI17		OSC1/CLKI (HS mode)	VSS	—	0.2 VDD	V	
	VIH	**Input High Voltage(2)**					
DI20		I/O Pins with ST Buffer:					
		without 5V Tolerance	0.8 VDD	—	VDD	V	
		with 5V Tolerance	0.8 VDD	—	5.5	V	
DI25		$\overline{\text{MCLR}}$	0.8 VDD	—	VDD	V	
DI26		OSCI/CLKI (XT mode)	0.7 VDD	—	VDD	V	
DI27		OSC1/CLKI (HS mode)	0.7 VDD	—	VDD	V	
DI30	ICNPU	**CNPUx Pull-up Current**	—	350	—	µA	VPIN = 0V, VDD = 3.3V
DI30A	ICNPD	**CNPDx Pull-Down Current**	—	300	—	µA	VPIN = 3.3V, VDD = 3.3V
	IIL	**Input Leakage Current**					
DI50		I/O Pins – 5V Tolerant	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V, pin at high-impedance
DI51		I/O Pins – Not 5V Tolerant	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V, pin at high-impedance
DI55		$\overline{\text{MCLR}}$	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V
DI56		OSC1/CLKI	—	0.1	1.0	µA	VPIN = 3.3V, VDD = 3.3V

Note 1: Data in the "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Refer to Table 1-1 for I/O pin buffer types.

FIGURE 26-5: TIMER1 EXTERNAL CLOCK TIMING CHARACTERISTICS

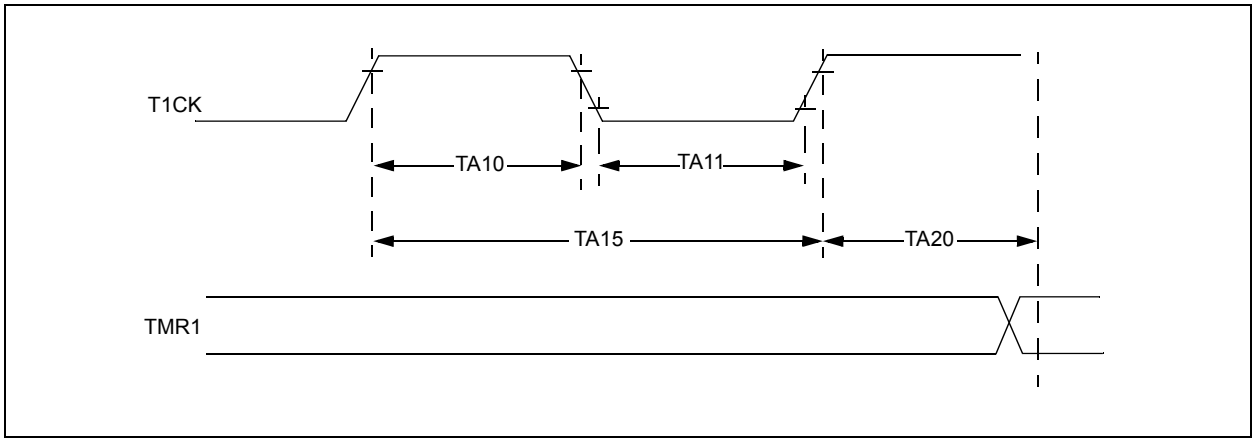


TABLE 26-23: MCCP/SCCP TIMER1 EXTERNAL CLOCK TIMING CHARACTERISTICS

Operating Conditions: 2.0V ≤ VDD ≤ 3.6V, -40°C ≤ TA ≤ +85°C (unless otherwise stated)							
Param. No.	**Symbol**	**Characteristics(1)**		**Min**	**Max**	**Units**	**Conditions**
TA10	TCKH	T1CK High Time	Synchronous	1	—	TPBCLK	Must also meet Parameter TA15
			Asynchronous	10	—	ns	
TA11	TCKL	T1CK Low Time	Synchronous	1	—	TPBCLK	Must also meet Parameter TA15
			Asynchronous	10	—	ns	
TA15	TCKP	T1CK Input Period	Synchronous	2	—	TPBCLK	
			Asynchronous	20	—	ns	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		—	3	TPBCLK	Synchronous mode

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 26-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

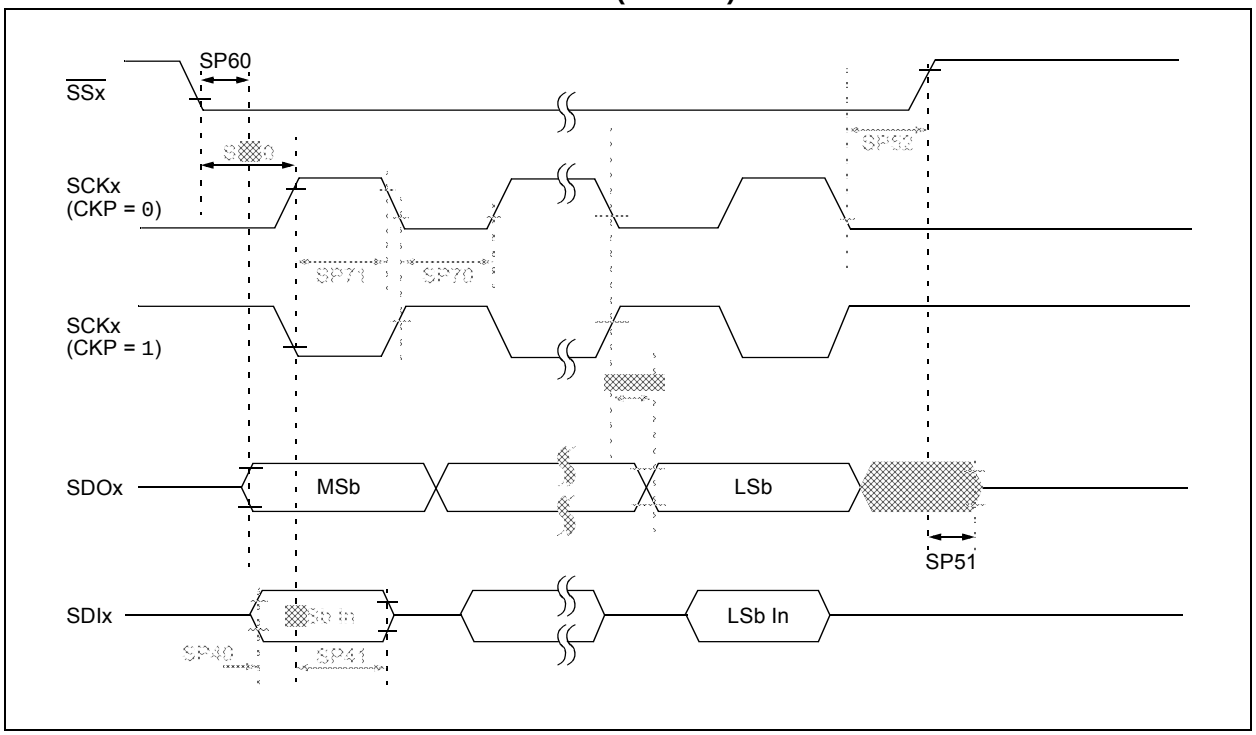


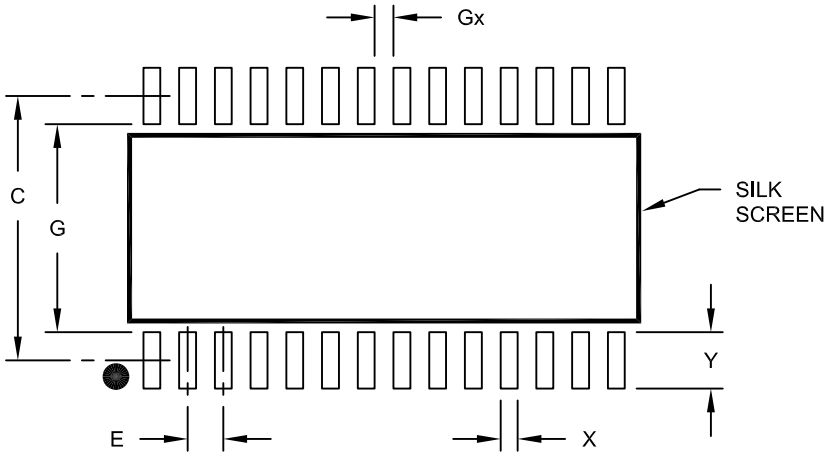
TABLE 26-29: SPIx MODULE SLAVE MODE TIMING REQUIREMENTS

Operating Conditions: 2.0V ≤ V_{DD} ≤ 3.6V, -40°C ≤ T_A ≤ +85°C (unless otherwise stated)					
Param.No.	**Symbol**	**Characteristics(1)**	**Min**	**Max**	**Units**
SP70	TscL	SCKx Input Low Time	10	—	ns
SP71	TscH	SCKx Input High Time	10	—	ns
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	ns
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	0	—	ns
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	7	—	ns
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↓ or SCKx ↑ Input	40	—	ns
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	2.5	12	ns
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	10	—	ns
SP60	TssL2doV	SDOx Data Output Valid after $\overline{SSx}$ Edge	—	12.5	ns

Note 1: These parameters are characterized but not tested in manufacturing.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A